

**AMENDMENTS TO THE CLAIMS**

**This listing of claims will replace all prior versions and listings of claims in the application:**

**LISTING OF CLAIMS:**

1. (currently amended): A compression bonding method comprising:  
disposing a plurality of metal bonding film shapes in a pattern directly on a substrate; and  
disposing a bonded element above the plurality of metal bonding film shapes and  
applying heat to the substrate and pressure to the bonded element, thereby bonding the bonded element to the substrate having the plurality of metal bonding film shapes,  
wherein the bonded element is plate shaped.
2. (previously presented): A compression bonding method comprising:  
disposing a first plurality of metal bonding film shapes in a pattern on a substrate and  
disposing a second plurality of metal bonding film shapes in a pattern on a bonded element; and  
disposing the bonded element above the first plurality of metal bonding film shapes and  
applying heat to the substrate and pressure to the bonded element, thereby bonding the bonded element having the second plurality of metal bonding film shapes to the substrate having the first plurality of metal bonding film shapes,  
wherein the first plurality of metal bonding film shapes are spaced apart from each other.

3. (previously presented): The compression bonding method of claim 1, wherein the substrate is made of a material selected from the group consisting of silicon, metal, and ceramic.

4. (previously presented): The compression bonding method of claim 1, wherein the metal bonding film is made of a material selected from the group consisting of aluminum, magnesium, zinc, and titanium.

5. (previously presented): The compression bonding method of claim 1, wherein the plurality of metal bonding film shapes are stripes or dots.

6. (previously presented): The compression bonding method of claim 1, wherein the bonded element is glass or metal.

7. (previously presented): The compression bonding method of claim 1, wherein the heat is lower than 350°C.

8. (previously presented): The compression bonding method of claim 1, wherein the bonded element contacts more than one of the plurality of metal bonding film shapes.

9. (previously presented): The compression bonding method of claim 2, wherein the substrate is made of a material selected from the group consisting of silicon, metal, and ceramic.

10. (previously presented): The compression bonding method of claim 2, wherein the first and second plurality of metal bonding film shapes are made of a material selected from the group consisting of aluminum, magnesium, zinc, and titanium.

11. (previously presented): The compression bonding method of claim 2, wherein the first and second plurality of metal bonding film shapes are stripes or dots.

12. (previously presented): The compression bonding method of claim 2, wherein the bonded element is glass or metal.

13. (previously presented): The compression bonding method of claim 2, wherein the heat is lower than 350°C.

14. (previously presented): The compression bonding method claim 2, wherein the bonded element contacts more than one of the first and second plurality of metal bonding film shapes.